

ABSTRACT OF THE DISCLOSURE

A substrate (wafer) processing method capable of producing an ink jet recording head substrate in which the reverse surface thereof, that is, the

5 surface having the larger of the two openings of the ink supply hole, is precisely covered by protective film to the very edge of the hole, comprising: a step for forming protective film on the substrate; a step for etching the surface of the protective film; a step

10 for forming etching resistant film on the etched surface of the protective film; a step for forming an ink supply hole pattern through the etchant-resistant film and protective film; a step for forming the ink supply hole through the substrate by etching; a step

15 for removing the portion of the protective film left projecting into the ink supply hole while forming the ink supply hole; and a step for removing the etchant-resistant film.

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